

Title (en)

COOLING DEVICE FOR ELECTRONIC COMPONENTS

Title (de)

KÜHLVORRICHTUNG FÜR ELEKTRONISCHE BAUELEMENTE

Title (fr)

DISPOSITIF DE REFROIDISSEMENT POUR COMPOSANTS ELECTRONIQUES

Publication

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Application

**EP 01913851 A 20010308**

Priority

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Abstract (en)

[origin: WO0169360A1] The invention relates to a cooling device for electronic components, especially for cooling microprocessors. The inventive device has at least one passive heat-conducting cooling element (12). At least one part of the passive cooling element (12) is connected to at least one heat transmission medium (20) which is in a solid state of aggregation and is a phase change material (PCM) having a heat receiving capacity that is many times higher compared to water and is configured as a PCM device. The heat transmission medium (20) stores the heat quantity which is produced by charging the electronic component and cannot be received and discharged by the passive cooling element (18) any longer, whereby the solid state of aggregation is maintained. Said medium releases said heat when the electronic component is charged less.

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